

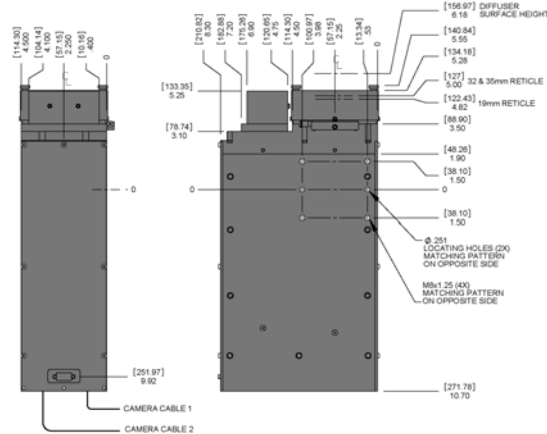
UltraVim Plus Vision Module

The UltraVim Plus inspects a variety of device packages including BGA, CSP, QFP, TSOP and J-Lead devices in three dimensions. Standard device file libraries provide for easy setup and training. Custom telecentric optics automatically compensate for changes in device height to provide true 3D metrology data. Digital I/O signals allow your handler to communicate with the system to reject failed devices.



UltraVim Plus Features

- Patented Vision Technology
- 1600x1200 Digital Cameras
- Easy Setup and Training
- Extensive Data, Charts & Reports
- Integrated Mark Inspection Option
- Multiple Language Options
- Windows XP Interface



				TYPICAL ACCURACY (microns)	
				BGA / CSP	QFP / TSOP
				Coplanarity 6	Coplanarity 6
				Warpage 6	Warpage 6
				Ball Height 9	Standoff 13
				X Error 6	Bent Lead 6
				Y Error 6	Pitch 9
				R Error 9	Skew 9
				XTP Error 9	Width 6
				YTP Error 9	Burr 13
				RTP Error 13	Tip Error 6
				Ball Diameter 6	Tip Offset 6
				X Diameter 6	Terminal Dim. 13
				Y Diameter 6	Total Pitch 13
				Ball Pitch 9	Lead Sweep 13
				X Pitch 9	Lead Slant 13
				Y Pitch 9	Lead Space 9
				X Grid Offset 6	
				Y Grid Offset 6	
				Board Width 13	
				Board Length 13	

For more information or a quotation, please contact us:

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